



**GENERAL DESCRIPTION**

The ICS844003I is a 3 differential output LVDS Synthesizer designed to generate Ethernet reference clock frequencies and is a member of the HiPerClocks™ family of high performance clock solutions from ICS. Using a 31.25MHz or 26.041666MHz, 18pF parallel resonant crystal, the following frequencies can be generated based on the settings of 4 frequency select pins (DIV\_SEL[A1:A0], DIV\_SEL[B1:B0]): 625MHz, 312.5MHz, 156.25MHz, and 125MHz. The 844003I has 2 output banks, Bank A with 1 differential LVDS output pair and Bank B with 2 differential LVDS output pairs.

The two banks have their own dedicated frequency select pins and can be independently set for the frequencies mentioned above. The ICS844003I uses ICS' 3rd generation low phase noise VCO technology and can achieve 1ps or lower typical rms phase jitter, easily meeting Ethernet jitter requirements. The ICS844003I is packaged in a small 24-pin TSSOP package.

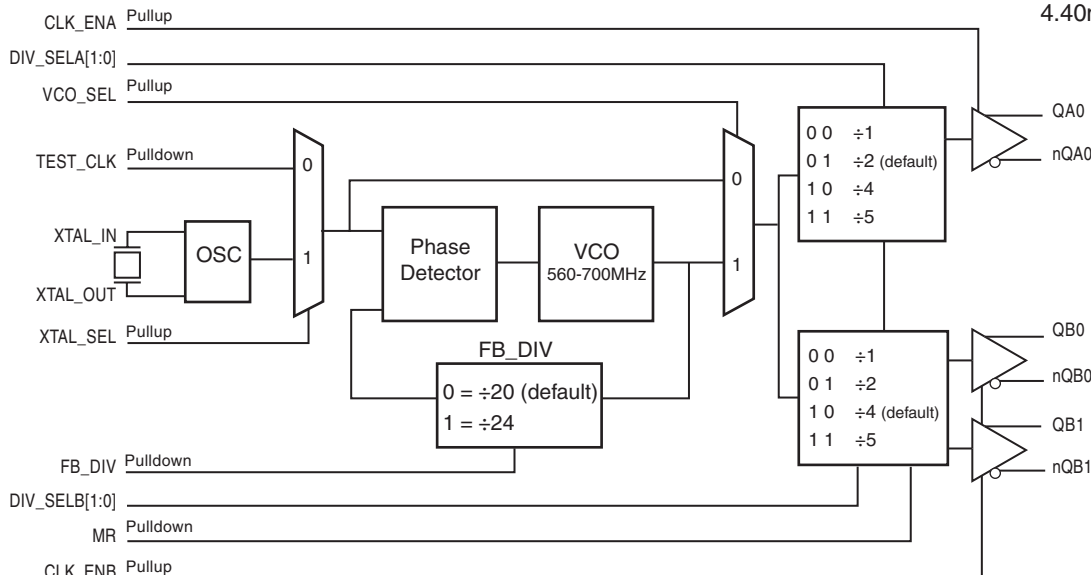
**FEATURES**

- Three LVDS outputs on two banks, A Bank with one LVDS pair and B Bank with 2 LVDS output pairs
- Using a 31.25MHz or 26.041666MHz crystal, the two output banks can be independently set for 625MHz, 312.5MHz, 156.25MHz or 125MHz
- Selectable crystal oscillator interface or LVCMOS/LVTTL single-ended input
- VCO range: 560MHz to 700MHz
- RMS phase jitter @ 156.25MHz (1.875MHz - 20MHz): 0.63ps (typical)
- 3.3V output supply mode
- -40°C to 85°C ambient operating temperature
- Available in both standard and lead-free RoHS-compliant packages

**PIN ASSIGNMENT**

DIV_SELB0	1	24	DIV_SELB1
VCO_SEL	2	23	VDDO_B
MR	3	22	QB0
VDDO_A	4	21	nQB0
QA0	5	20	QB1
nQA0	6	19	nQB1
CLK_ENB	7	18	XTAL_SEL
CLK_ENA	8	17	TEST_CLK
FB_DIV	9	16	XTAL_IN
VDDA	10	15	XTAL_OUT
VDD	11	14	GND
DIV_SELA0	12	13	DIV_SELA1

**BLOCK DIAGRAM**



**ICS844003I**

**24-Lead TSSOP**

4.40mm x 7.8mm x 0.92mm  
package body  
**G Package**  
Top View

The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.



**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1 24	DIV_SELB0 DIV_SELB1	Input	Pulldown	Division select pin for Bank B. Default = Low. LVCMOS/LVTTL interface levels.
2	VCO_SEL	Input	Pullup	VCO select pin. When Low, the PLL is bypassed and the crystal reference or TEST_CLK (depending on XTAL_SEL setting) are passed directly to the output dividers. Has an internal pullup resistor so the PLL is not bypassed by default. LVCMOS/LVTTL interface levels.
3	MR	Input	Pulldown	Active HIGH Master Reset. When logic HIGH, the internal dividers are reset causing the true outputs Qx to go low and the inverted outputs nQx to go high. When logic LOW, the internal dividers and the outputs are enabled. Has an internal pulldown resistor so the power-up default state of outputs and dividers are enabled. LVCMOS/LVTTL interface levels.
4	V <sub>DDO_A</sub>	Power		Output supply pin for Bank A outputs.
5, 6	QA0, nQA0	Output		Differential output pair. LVDS interface levels.
7	CLK_ENB	Input	Pullup	Output enable Bank B. Active High outputs are enable. When logic HIGH, the output pairs on Bank B are enabled. When logic LOW, the output pairs are in a high impedance state. Has an internal pullup resistor so the default power-up state of outputs are enabled. LVCMOS/LVTTL interface levels.
8	CLK_ENA	Input	Pullup	Output enable Bank A. Active High output enable. When logic HIGH, the output pair in Bank A is enabled. When logic LOW, the output pair is in a high impedance state. Has an internal pullup resistor so the default power-up state of output is enabled. LVCMOS/LVTTL interface levels.
9	FB_DIV	Input	Pulldown	Feedback divide select. When Low (default), the feedback divider is set for ÷20. When HIGH, the feedback divider is set for ÷24. LVCMOS/LVTTL interface levels.
10	V <sub>DDA</sub>	Power		Analog supply pin.
11	V <sub>DD</sub>	Power		Core supply pin.
12 13	DIV_SELA0 DIV_SELA1	Input	Pullup	Division select pin for Bank A. Default = HIGH. LVCMOS/LVTTL interface levels.
14	GND	Power		Power supply ground.
15, 16	XTAL_OUT, XTAL_IN	Input		Parallel resonant crystal interface. XTAL_OUT is the output, XTAL_IN is the input. XTAL_IN is also the overdrive pin if you want to overdrive the crystal circuit with a single-ended reference clock.
17	TEST_CLK	Input	Pulldown	Single-ended reference clock input. Has an internal pulldown resistor to pull to low state by default. Can leave floating if using the crystal interface. LVCMOS/LVTTL interface levels.
18	XTAL_SEL	Input	Pullup	Crystal select pin. Selects between the single-ended TEST_CLK or crystal interface. Has an internal pullup resistor so the crystal interface is selected by default. LVCMOS/LVTTL interface levels.
19, 20	nQB1, QB1	Output		Differential output pair. LVDS interface levels.
21, 22	nQB0, QB0	Output		Differential output pair. LVDS interface levels.
23	V <sub>DDO_B</sub>	Power		Output supply pin for Bank B outputs.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ



**TABLE 3A. BANK A FREQUENCY TABLE**

Inputs				Feedback Divider	Bank A Output Divider	M/N Multiplication Factor	QA0/nQA0 Output Frequency (MHz)
Crystal Frequency (MHz)	DIV_SELA1	DIV_SELA0	FB_DIV				
31.25	0	0	0	20	1	20	625
31.25	0	1	0	20	2	10	312.5
31.25	1	0	0	20	4	5	156.25
31.25	1	1	0	20	5	4	125
26.041666	0	0	1	24	1	24	625
26.041666	0	1	1	24	2	12	312.5
26.041666	1	0	1	24	4	6	156.25
26.041666	1	1	1	24	5	64.8	125

**TABLE 3B. BANK B FREQUENCY TABLE**

Inputs				Feedback Divider	Bank B Output Divider	M/N Multiplication Factor	QB0/nQB0 Output Frequency (MHz)
Crystal Frequency (MHz)	DIV_SELB1	DIV_SELB0	FB_DIV				
31.25	0	0	0	20	1	20	625
31.25	0	1	0	20	2	10	312.5
31.25	1	0	0	20	4	5	156.25
31.25	1	1	0	20	5	4	125
26.041666	0	0	1	24	1	24	625
26.041666	0	1	1	24	2	12	312.5
26.041666	1	0	1	24	4	6	156.25
26.041666	1	1	1	24	5	4.8	125

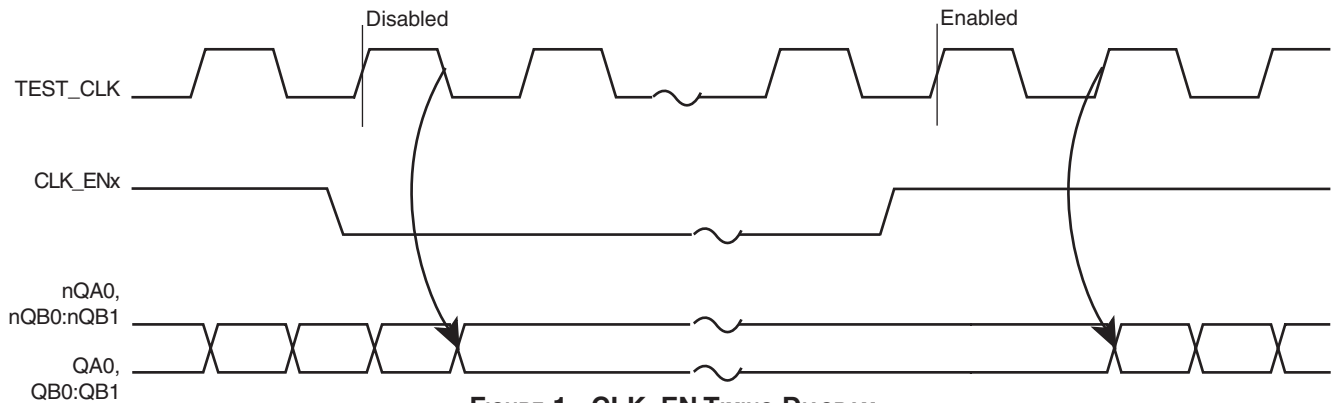


**TABLE 3C. OUTPUT BANK CONFIGURATION SELECT FUNCTION TABLE**

Inputs		Outputs	Inputs		Outputs
DIV_SELA1	DIV_SELA0	QA	DIV_SELB1	DIV_SELB0	QB
0	0	÷1	0	0	÷1
0	1	÷2	0	1	÷2
1	0	÷4	1	0	÷4
1	1	÷5	1	1	÷5

**TABLE 3D. FEEDBACK DIVIDER CONFIGURATION SELECT FUNCTION TABLE**

Inputs	
FB_DIV	Feedback Divide
0	÷20
1	÷24



**FIGURE 1. CLK\_EN TIMING DIAGRAM**

**TABLE 3E. CLK\_ENA SELECT FUNCTION TABLE**

Inputs	Outputs	
CLK_ENA	QA0	nQA0
0	LOW	HIGH
1	Active	Active

**TABLE 3F. CLK\_ENB SELECT FUNCTION TABLE**

Inputs	Outputs	
CLK_ENB	QB0:QB1	nQB0:nQB1
0	LOW	HIGH
1	Active	Active



**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage, $V_{DD}$	4.6V
Inputs, $V_i$	-0.5V to $V_{DD} + 0.5V$
Outputs, $I_o$	
Continuous Current	10mA
Surge Current	15mA
Package Thermal Impedance, $\theta_{JA}$	70°C/W (0 lfpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 4A. POWER SUPPLY DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = V_{DDO\_A} = V_{DDO\_B} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{DD}$	Core Supply Voltage		3.135	3.3	3.465	V
$V_{DDA}$	Analog Supply Voltage		3.135	3.3	3.465	V
$V_{DDO\_A, B}$	Output Supply Voltage		3.135	3.3	3.465	V
$I_{DD}$	Power Supply Current			99		mA
$I_{DDA}$	Analog Supply Current			10		mA
$I_{DDO\_A, B}$	Output Supply Current			52		mA

**TABLE 4B. LVCMOS / LVTTTL DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = V_{DDO\_A} = V_{DDO\_B} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{IH}$	Input High Voltage	$V_{DD} = 3.3V$	2		$V_{DD} + 0.3$	V
		$V_{DD} = 2.5V$	1.7		$V_{DD} + 0.3$	V
$V_{IL}$	Input Low Voltage	$V_{DD} = 3.3V$	-0.3		0.8	V
		$V_{DD} = 2.5V$	-0.3		0.7	V
$I_{IH}$	Input High Current	TEST_CLK, MR, FB_DIV DIV_SELA1, DIV_SELB0 $V_{DD} = V_{IN} = 3.465V$ or 2.625V			150	$\mu A$
		DIV_SELB1, DIV_SELA0, VCO_SEL, XTAL_SEL, CLK_ENA, CLK_ENB $V_{DD} = V_{IN} = 3.465V$ or 2.625V			5	$\mu A$
$I_{IL}$	Input Low Current	TEST_CLK, MR, FB_DIV DIV_SELA1, DIV_SELB0 $V_{DD} = 3.465V$ or 2.625V, $V_{IN} = 0V$	-5			$\mu A$
		DIV_SELB1, DIV_SELA0, VCO_SEL, XTAL_SEL, CLK_ENA, CLK_ENB $V_{DD} = 3.465V$ or 2.625V, $V_{IN} = 0V$	-150			$\mu A$



**TABLE 4C. LVDS DC CHARACTERISTICS,  $V_{DD} = V_{DDA} = V_{DDO\_A} = V_{DDO\_B} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{OD}$	Differential Output Voltage			350		mV
$\Delta V_{OD}$	$V_{OD}$ Magnitude Change			0	40	mV
$V_{OS}$	Offset Voltage			1.4		V
$\Delta V_{OS}$	$V_{OS}$ Magnitude Change			0	50	mV

**TABLE 5. CRYSTAL CHARACTERISTICS**

Parameter	Test Conditions	Minimum	Typical	Maximum	Units
Mode of Oscillation		Fundamental			
Frequency	FB_DIV = $\pm 20$	28		35	MHz
	FB_DIV = $\pm 24$	23.33		29.16	MHz
Equivalent Series Resistance (ESR)				50	$\Omega$
Shunt Capacitance				7	pF
Drive Level				1	mW

NOTE: Characterized using an 18pF parallel resonant crystal.

**TABLE 6. AC CHARACTERISTICS,  $V_{DD} = V_{DDA} = V_{DDO\_A} = V_{DDO\_B} = 3.3V \pm 5\%$ ,  $T_A = -40^\circ C$  TO  $85^\circ C$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$f_{OUT}$	Output Frequency Range	Output Divider = $\pm 1$	560		700	MHz
		Output Divider = $\pm 2$	280		350	MHz
		Output Divider = $\pm 4$	140		175	MHz
		Output Divider = $\pm 5$	112		140	MHz
$t_{sk}(b)$	Bank Skew, NOTE 1		3		ps	
$t_{sk}(o)$	Output Skew; NOTE 2, 4	Outputs @ Same Frequency		15		ps
		Outputs @ Different Frequencies		30		ps
$f_{jit}(\emptyset)$	RMS Phase Jitter (Random); NOTE 3	625MHz (1.875MHz - 20MHz)		0.55		ps
		312.5MHz (1.875MHz - 20MHz)		0.59		ps
		156.25MHz (1.875MHz - 20MHz)		0.63		ps
		125MHz (1.875MHz - 20MHz)		0.64		ps
$t_R / t_F$	Output Rise/Fall Time	20% to 80%		325		ps
odc	Output Duty Cycle			50		%

NOTE 1: Defined as skew within a bank of outputs at the same voltages and with equal load conditions.

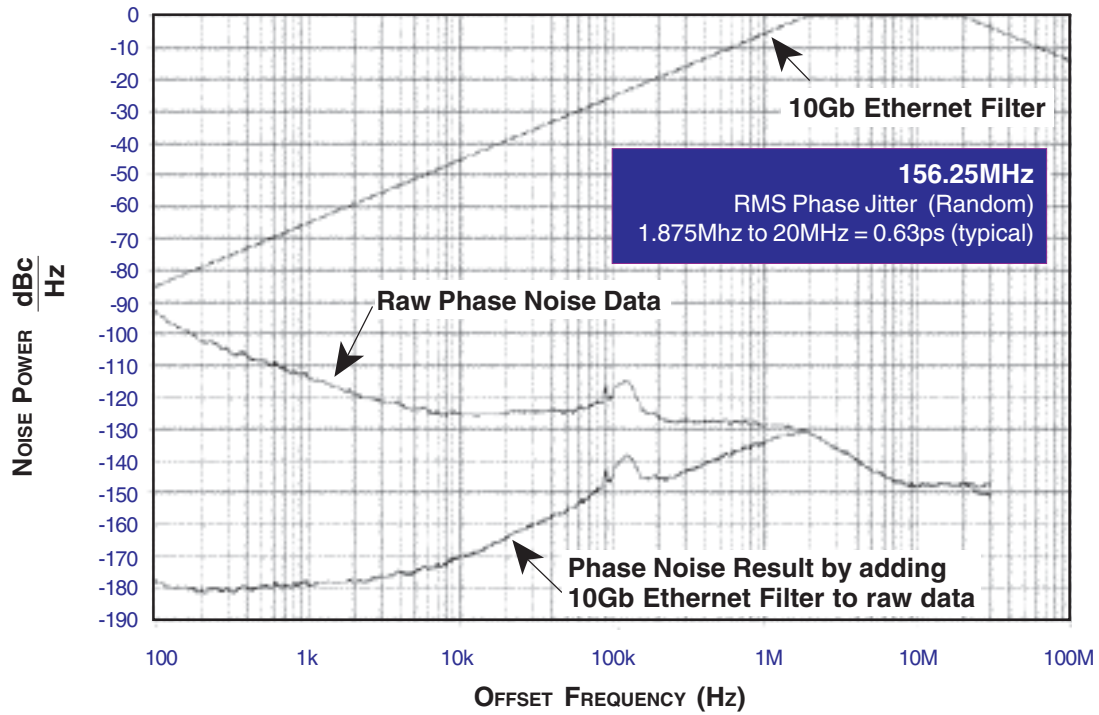
NOTE 2: Defined as skew between outputs at the same supply voltages and with equal load conditions. Measured at the output differential cross points.

NOTE 3: Please refer to the Phase Noise Plots.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

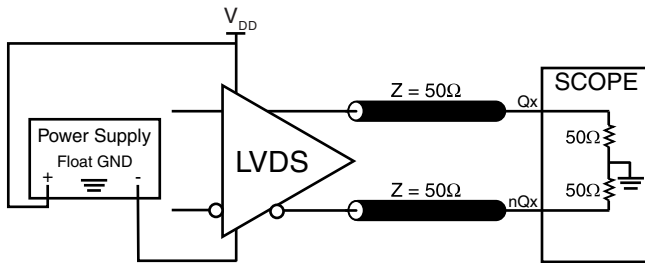


**TYPICAL PHASE NOISE AT 156.25MHz**

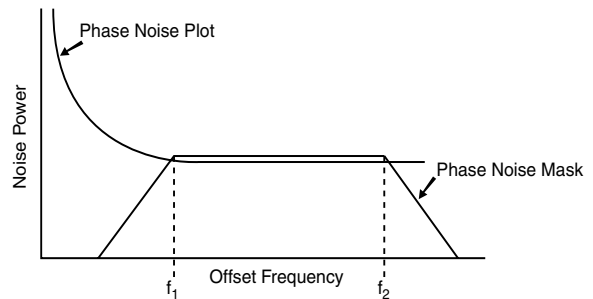




**PARAMETER MEASUREMENT INFORMATION**

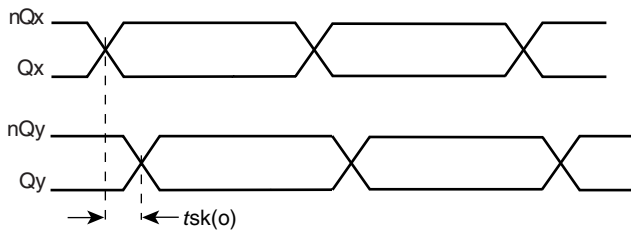


**LVDS 3.3V OUTPUT LOAD AC TEST CIRCUIT**

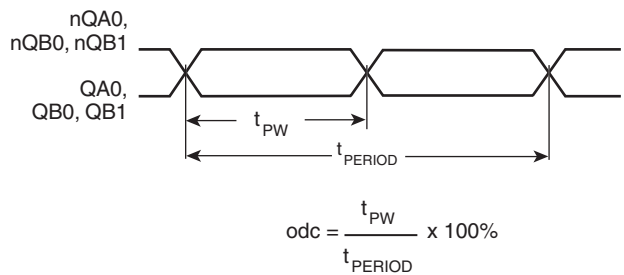


$$\text{RMS Jitter} = \sqrt{\text{Area Under the Masked Phase Noise Plot}}$$

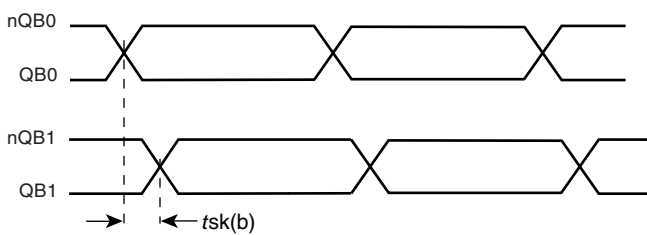
**RMS PHASE JITTER**



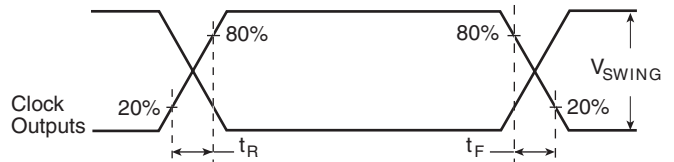
**OUTPUT SKEW**



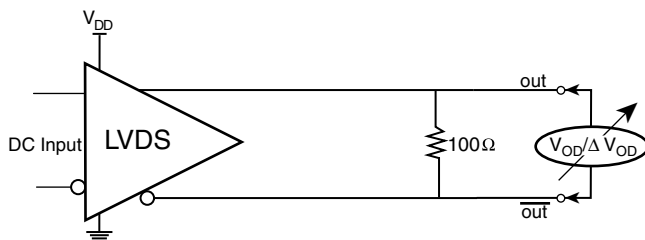
**OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD**



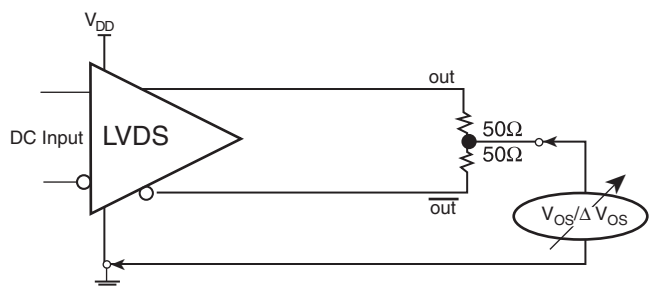
**BANK SKEW**



**OUTPUT RISE/FALL TIME**



**DIFFERENTIAL OUTPUT VOLTAGE SETUP**



**OFFSET VOLTAGE SETUP**

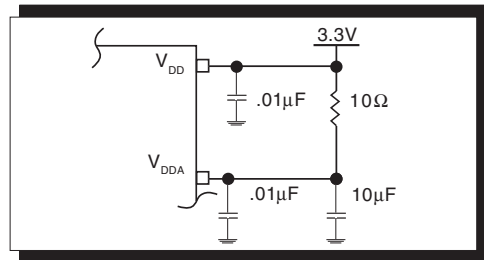




## APPLICATION INFORMATION

### POWER SUPPLY FILTERING TECHNIQUES

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. The ICS844003I provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL.  $V_{DD}$ ,  $V_{DDA}$ , and  $V_{DDOX}$  should be individually connected to the power supply plane through vias, and bypass capacitors should be used for each pin. To achieve optimum jitter performance, power supply isolation is required. *Figure 2* illustrates how a  $10\Omega$  resistor along with a  $10\mu\text{F}$  and a  $.01\mu\text{F}$  bypass capacitor should be connected to each  $V_{DDA}$  pin. The  $10\Omega$  resistor can also be replaced by a ferrite bead.

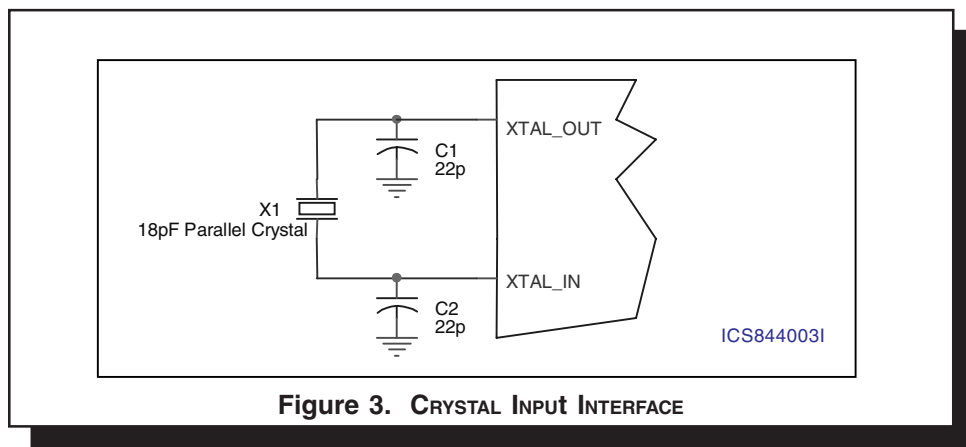


**FIGURE 2. POWER SUPPLY FILTERING**

### CRYSTAL INPUT INTERFACE

The ICS844003I has been characterized with 18pF parallel resonant crystals. The capacitor values shown in *Figure 3* below

were determined using a 31.25MHz or 26.041666MHz 18pF parallel resonant crystal and were chosen to minimize the ppm error.



**Figure 3. CRYSTAL INPUT INTERFACE**



**RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS**

**INPUTS:**

**CRYSTAL INPUT:**

For applications not requiring the use of the crystal oscillator input, both XTAL\_IN and XTAL\_OUT can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from XTAL\_IN to ground.

**TEST\_CLK INPUT:**

For applications not requiring the use of the test clock, it can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from the TEST\_CLK to ground.

**LVC MOS CONTROL PINS:**

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

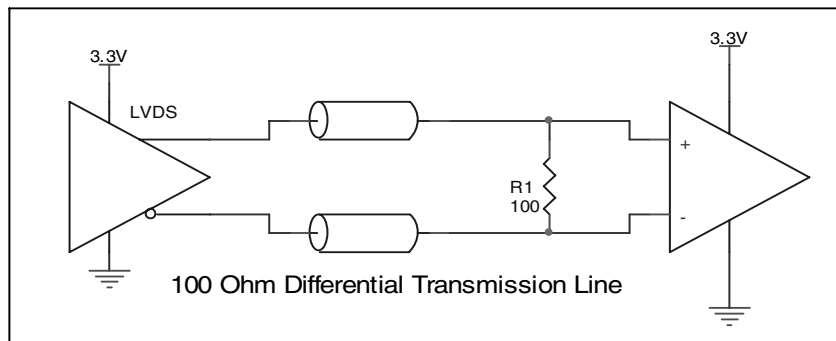
**OUTPUTS:**

**LVDS**

All unused LVDS output pairs can be either left floating or terminated with 100Ω across. If they are left floating, we recommend that there is no trace attached.

**3.3V LVDS DRIVER TERMINATION**

A general LVDS interface is shown in *Figure 4*. In a 100Ω differential transmission line environment, LVDS drivers require a matched load termination of 100Ω across near the receiver input.



**FIGURE 4. TYPICAL LVDS DRIVER TERMINATION**



Integrated  
Circuit  
Systems, Inc.

**PRELIMINARY**

**ICS844003I**  
FEMTOCLOCKS™ CRYSTAL-TO-LVDS  
FREQUENCY SYNTHESIZER

**RELIABILITY INFORMATION**

**TABLE 7.  $\theta_{JA}$  vs. AIR FLOW TABLE FOR 24 LEAD TSSOP**

$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2.5
Multi-Layer PCB, JEDEC Standard Test Boards	70°C/W	65°C/W	62°C/W

**TRANSISTOR COUNT**

The transistor count for ICS844003I is: 3394



PACKAGE OUTLINE - G SUFFIX FOR 24 LEAD TSSOP

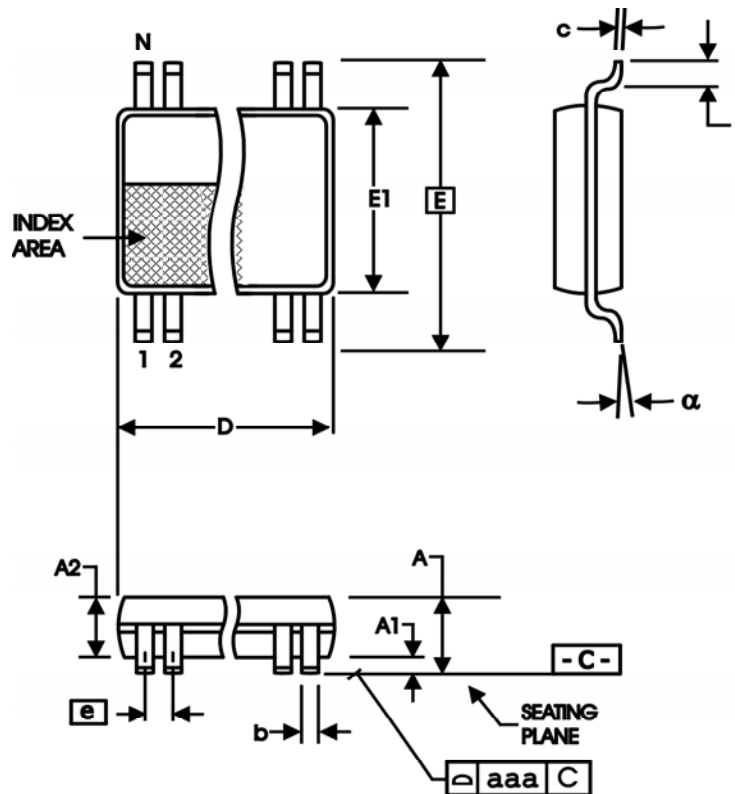


TABLE 8. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	24	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	7.70	7.90
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-153



Integrated  
Circuit  
Systems, Inc.

**PRELIMINARY**

**ICS844003I**  
FEMTOCLOCKS™ CRYSTAL-TO-LVDS  
FREQUENCY SYNTHESIZER

**TABLE 9. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS844003AGI	ICS844003AGI	24 Lead TSSOP	tube	-40°C to 85°C
ICS844003AGIT	ICS844003AGI	24 Lead	2500 tape & reel	-40°C to 85°C
ICS844003AGILF	TBD	24 Lead "Lead-Free" TSSOP	tube	-40°C to 85°C
ICS844003AGITLF	TBD	24 Lead "Lead-Free" TSSOP	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

The aforementioned trademarks, HiPerClockS and FemtoClocks are trademarks of Integrated Circuit Systems, Inc. or its subsidiaries in the United States and/or other countries. While the information presented herein has been checked for both accuracy and reliability, Integrated Circuit Systems, Incorporated (ICS) assumes no responsibility for either its use or for infringement of any patents or other rights of third parties, which would result from its use. No other circuits, patents, or licenses are implied. This product is intended for use in normal commercial and industrial applications. Any other applications such as those requiring high reliability or other extraordinary environmental requirements are not recommended without additional processing by ICS. ICS reserves the right to change any circuitry or specifications without notice. ICS does not authorize or warrant any ICS product for use in life support devices or critical medical instruments.